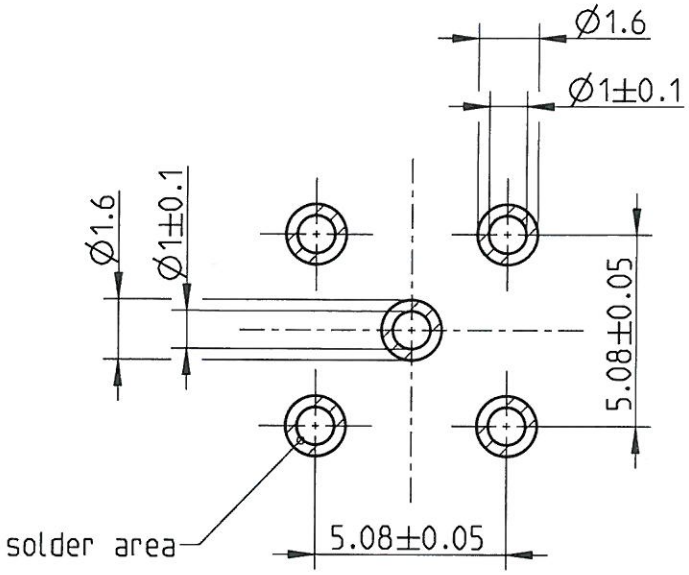
Leiterplatten-Layout
PCB layout
B 30c



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 m-H	RN 006-01 dimensions <0,5 and symmetry				scale: 5:1	weight[g]: surface[mm²]:
									material:	
					date	name			title:	
				drawn	22.11.2004	A_Nobis			Leiterplatten-Layout *PCB layout*	
				check.	9.1.06					
				appr.	09.01.06					
				dimensioning incl. finish						
c00	06-0011	A_Nobis	09.01.2006						part-no..: MB_30C	sheet: 1
b00	05-0593	A_Nobis	04.11.2005							of: 1
a00	04-0709	A_Nobis	22.11.2004	distribu-tion to:	FE	AZ	QSM	RMT	.	
rev.	change-no	name	date		X	.	.	.	.	remarks: .

-METRIC-

ISO-Projektion Methode E